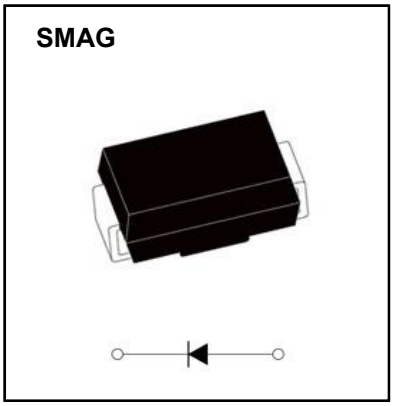
SZCJ

SMAG Plastic-Encapsulate Diodes

HD20G

General Purpose Rectifier Diodes



Features

- I_O 1A
- VRRM 2000V
- Low forward voltage drop
- High surge current capability
- Glass passivated chip junction

Applications

- Rectifier

Marking

- HD20G

Limiting Values(Absolute Maximum Rating)

Item	Symbol	Unit	Test Conditions	HD20G
Repetitive Peak Reverse Voltage	V_{RRM}	V		2000
Maximum RMS Voltage	V_{RMS}	V		1400
Maximum DC Blocking Voltage	V_{DC}	V		2000
Average Forward Current	$I_{F(AV)}$	A	60Hz Half-sine wave, Resistance load	1
Surge(Non-repetitive)Forward Current	I_{FSM}	A	60Hz Half-sine wave,1 cycle, Ta=25℃	30
Junction Temperature	T_J	℃		-55 ~ +150
Storage Temperature	T_{STG}	℃		-55 ~ +150

Electrical Characteristics (T=25℃ Unless otherwise specified)

Item	Symbol	Unit	Test Condition		Max
Peak Forward Voltage	V_F	V	I_{FM}=1.0A		1.2
Peak Reverse Current	I_{RRM1}	μA	· V_{RM}=V_{RRM}	Ta =25℃	5.0
	I_{RRM2}			Ta =125℃	50
Juction Capacitance (Typical)	Cj	pF	Measured at 1MHZ and Applied Reverse Voltage of 4.0 V.D.C.		5.0
Thermal Resistance (Typical)	$R_{\theta J-A}$	℃/W	Between junction and ambient		75
	$R_{\theta J-L}$		Between junction and terminal		27

Notes:

Thermal resistance from junction to ambient and from juction to lead mounted on FR4 PCB double sided copper mini pad

Typical Characteristics

FIG.1: FORWARD CURRENT DERATING CURVE

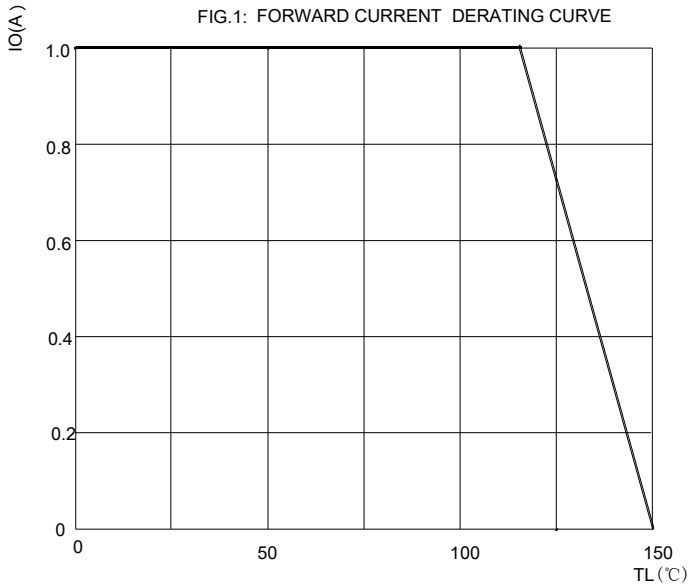


FIG.2: MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

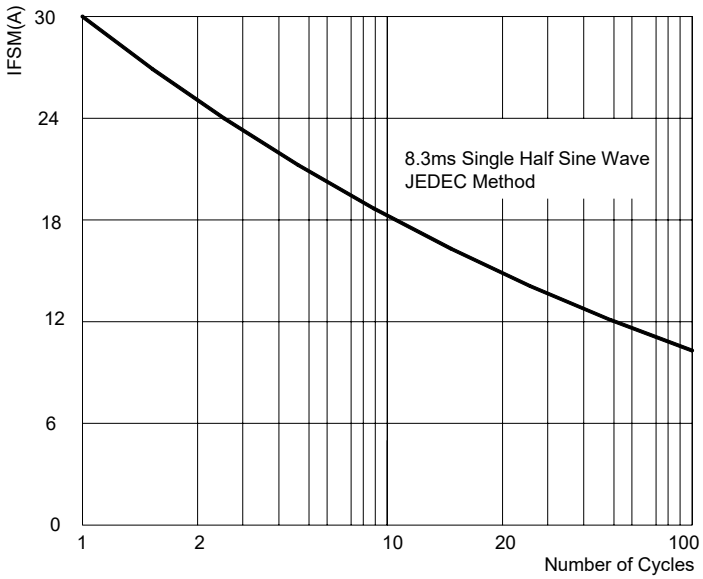


FIG.3: TYPICAL FORWARD CHARACTERISTICS

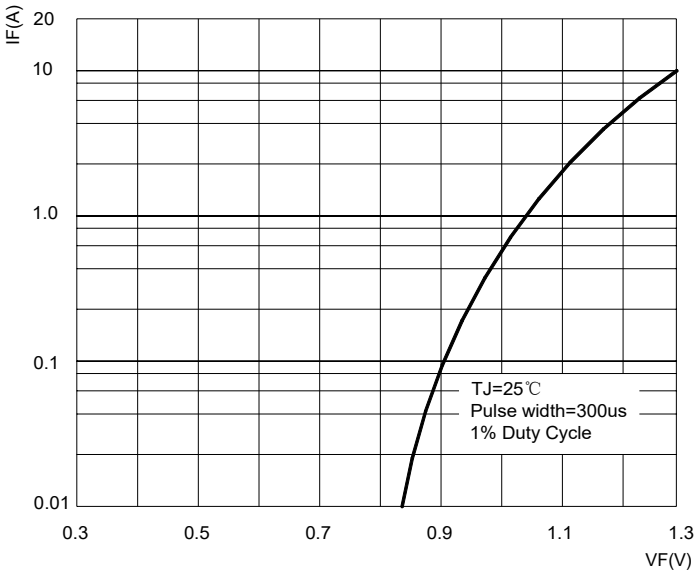
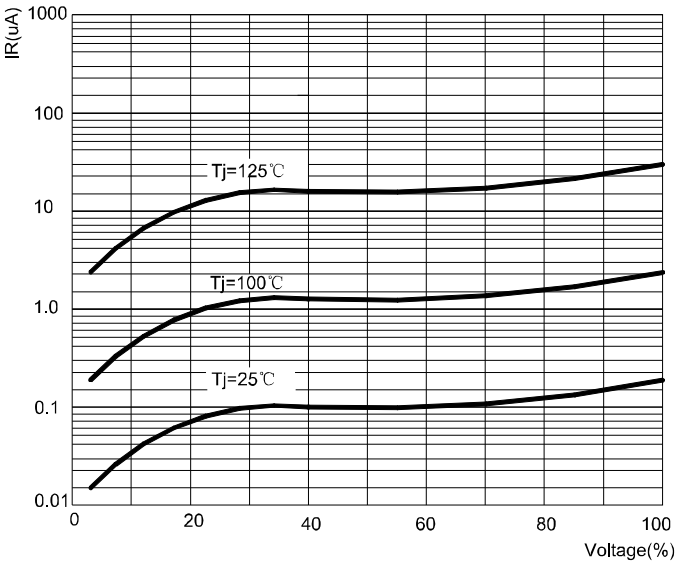
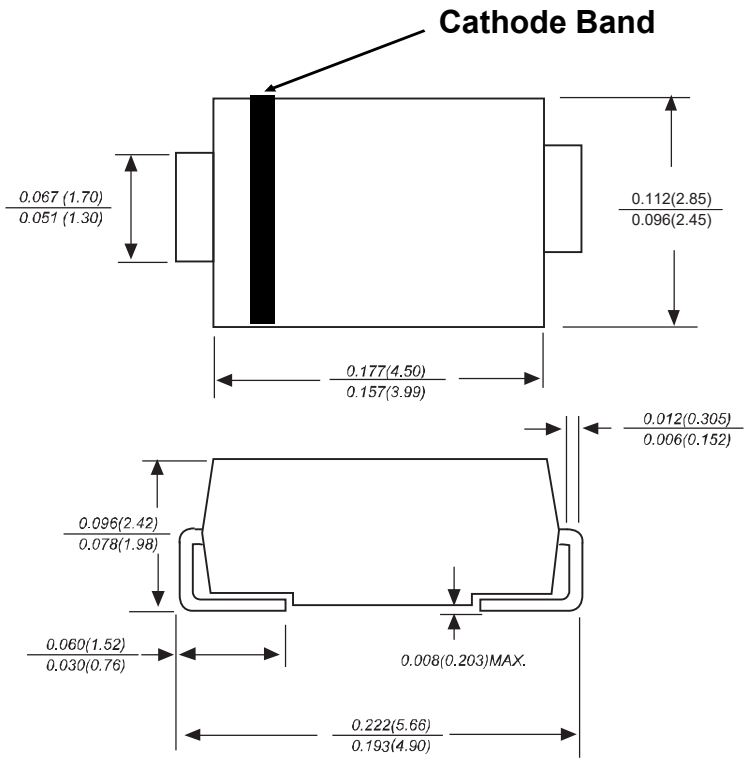


FIG.4:TYPICAL REVERSE CHARACTERISTICS

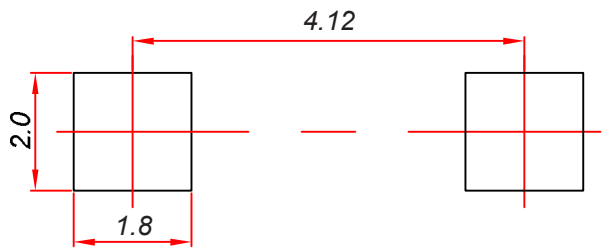


SMAG Package Outline Dimensions



Dimensions in inches and (millimeters)

SMAG Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.

NOTICE

SZCJ reserves the right to make modifications,enha nts,improvements,corrections or other es without further notice to any product herein.SZCJ does not assume any liability arising out of the application or use of any product described .

Reel Taping Specifications For Surface Mount Dev ices- SMAG

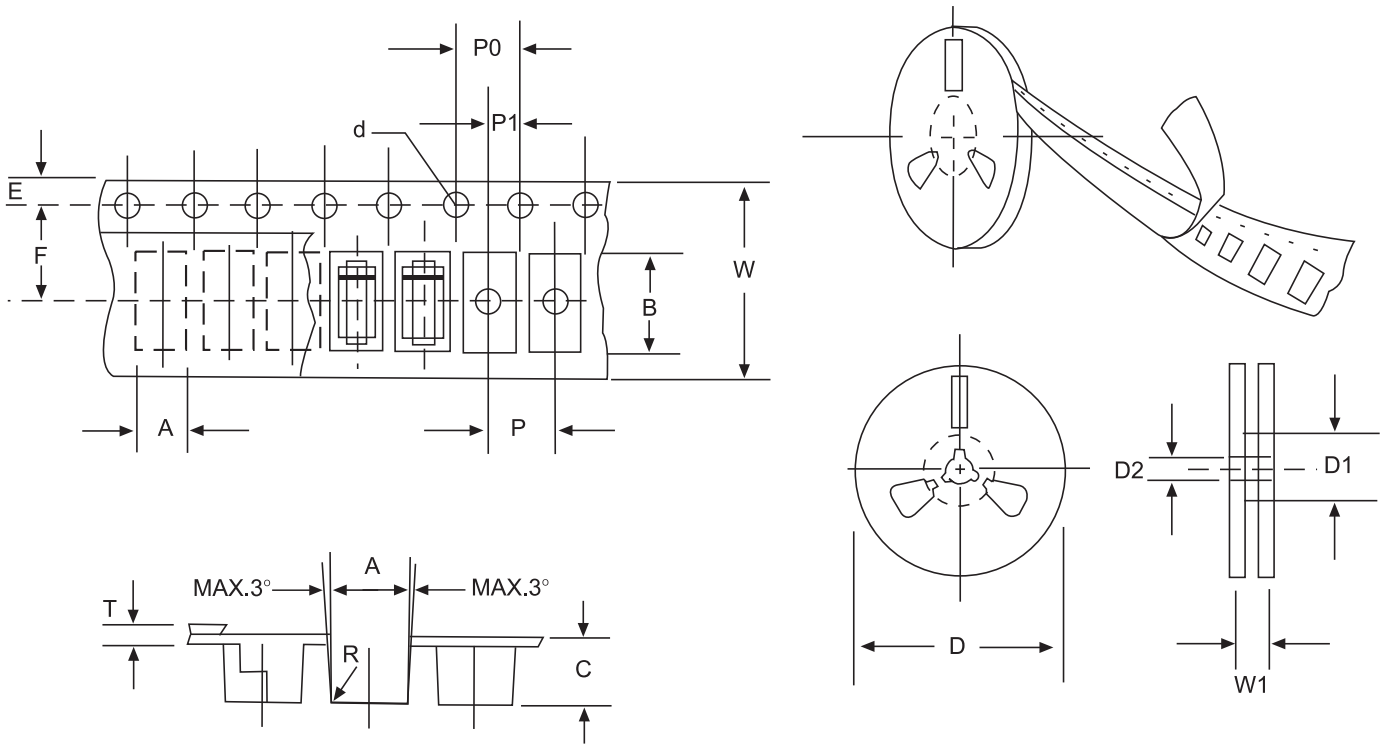


Fig:CONFIGURATION OF FLAT MELF TAPING

ITEM	SYMBOL	SMAG mm(inch)
Carrier width	A	2.79±0.1(0.110±0.004)
Carrier length	B	5.33±0.1(0.210±0.004)
Carrier depth	C	2.36±0.1(0.093±0.004)
Sprocket hole	d	1.55±0.05(0.061±0.002)
Reel outside diameter	D	279±2.0 (11± 0.079)
Reel inner diameter	D1	75±1.0 (2.95 ±0.039)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Stroket hole position	E	1.75±0.1(0.069±0.004)
Punch hole position	F	5.5±0.05(0.217±0.002)
Punch hole pitch	P	4.0±0.1(0.157±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Totall tape thickness	T	0.28±0.02(0.011±0.0008)
Tape width	W	12.0±0.2(0.472±0.008)
Reel width	W1	16.8±2.0(0.661±0.079)

NOTE:Devices are packde in accordance with EIA standard RS-481-A and specification given above.